

■ Fujitsu Group specified Banned Substances

Fujitsu group defines the substances which are harmful to human health and the environment as "Fujitsu Group specified Banned Substances", and we have been offering the products which don't contain them by working on the strict elimination through our green product assessment and green procurement activity. "Fujitsu Group specified Banned Substances" consists of global common core banned substances and regional specific banned substances. Target substances are as follows.

**“Table 1: A. Global Common Banned Substances”**

No.	Substance Name	Banned Standards	Remarks
A001	Asbestos	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
A002	Azocolorants and Azodyes which form certain aromatic amines	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	This applies to cases that azo dyes and azo pigments are used for leather products, textile products or their parts that are possible to contact human skins directly for a long time and that form specified amines listed in Table 1a as a result of decomposition of azo group.
A003	Cadmium / Cadmium Compounds	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> <li>3. Concentration in Material must not exceed 100 ppm even contained as impurities.</li> <li>4. Sum of concentration in Packaging Material of the 4 substances<sup>(*)</sup> must not exceed 100 ppm even contained as impurities</li> </ol>	Refer to Exempted Application in Table 1g.
A004	Chromium VI compounds	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> <li>3. Concentration in Material must not exceed 1000 ppm even contained as impurities.</li> <li>4. Sum of concentration in Packaging Material of the 4 substances<sup>(*)</sup> must not exceed 100 ppm even contained as impurities</li> </ol>	
A005	Lead / Lead Compounds	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> <li>3. Concentration in Material must not exceed 1000 ppm even contained as impurities. In this regard, however, concentration in Material must not exceed 300 ppm in the case of PVC (Polyvinyl Chloride) cable.</li> <li>4. Sum of concentration in Packaging Material of the 4 substances<sup>(*)</sup> must not exceed 100 ppm even contained as impurities</li> </ol>	Exempted Application: Table 1g.
A006	Mercury / Mercury Compounds	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> <li>3. Concentration in Material must not exceed 1000 ppm even contained as impurities.</li> <li>4. Sum of concentration in Packaging Material of the 4 substances<sup>(*)</sup> must not exceed 100 ppm even contained as impurities</li> </ol>	Exempted Application: Table 1g.

No.	Substance Name	Banned Standards	Remarks
A007	Ozone Depleting Substances (CFCs, HCFCs, HBFCs, carbon tetrachloride, etc.) Details: Table 1b.	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
A008	PFOS / PFOS-related substances	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process. 3. Concentration must not exceed the following levels even contained as impurities - 0.1% by weight. - Only ink or tonner: 0.005% by weight. - Amount in the coated materials: 1□g/m <sup>2</sup>	Exempted Application: Table 1g.
A009	Polybrominated Biphenyls (PBBs)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process. 3. Concentration in Material must not exceed 1000 ppm even contained as impurities.	
A010	Polybrominated Diphenylethers (PBDEs)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process. 3. Concentration in Material must not exceed 1000 ppm even contained as impurities.	
A011	Polychlorinated Biphenyls (PCBs) and specific substitutes Details: Table 1c.	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
A012	Polychlorinated Terphenyls (PCTs)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
A013	Shortchain Chlorinated Paraffins (C10-C13)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
A014	Tri-substituted organostannic compounds (except for TBTO)	Concentration in Product must not exceed 1000 ppm .	
A015	Tributyl Tin Oxide (TBTO)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
A016	Dimethylfumarate (DMF)	Concentration in a product must not exceed 0.1 ppm.	
A017	Dibutyltin compounds (DBT)	Concentration in Product must not exceed 1000 ppm.	Exempted Application: Table 1g.
A018	Diocetyl tin compounds (DOT)	Concentration in Product must not exceed 1000 ppm.	This applies to cases that are used for textile, leather products or their parts intended to come into contact with the skin directly, and the case that are used for two-component room temperature vulcanisation moulding kits (RTV-2 moulding kits).
A019	Fluorinated greenhouse gases (HFC, PFC, SF6) Details: Table 1d.	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	This applies to cases that are used for one component foams.

No.	Substance Name	Banned Standards	Remarks
A020	Formaldehyde	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process. 3. Concentration in Material must not exceed 75 ppm even contained as impurities.	This applies to cases that are used for textile products or their parts.
A021	Tris(2,3-dibromopropyl)phosphate (TRIS)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	This applies to cases that are used for textile products or their parts intended to come into contact with the skin directly.
A022	Tris(1-aziridiny) phosphine oxide (TEPA)	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	This applies to cases that are used for textile products or their parts intended to come into contact with the skin directly.
A023	Nickel	1. Ban of use as stainless steels or nickel plating.	This applies to cases that are used for regions where prolonged skin contact is expected <sup>(*)2</sup> .
A024	Polycyclic aromatic hydrocarbons (PAH) Details: Table 1e.	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process. 3. Concentration must not exceed 0,0001 % by weight of rubber or plastic component even contained as impurities.	This applies to rubber or plastic component where direct and prolonged contact, or repeated in short-term contact with the human skin or the oral cavity are expected. <sup>(*)3</sup>  In force from 27th December 2015
A025	Hexabromocyclododecane (HBCDD) Details: Table 1f.	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	

(\*1) In the case of packaging materials, 4 substances are Cadmium / Cadmium compounds, Chromium IV compounds, Lead / Lead compounds and Mercury / Mercury compounds.

(\*2) Regions where prolonged skin contact is expected are the most outside surface of the following:  
Keyboard, mouse, palm rest of laptop, chassis of mobile phone and liquid crystal touch panel.

(\*3) Rubber or plastic component where direct and prolonged contact, or repeated in short-term contact with the human skin or the oral cavity are expected are the following:  
Rubber or plastic material of the most outside surface of keyboard, mouse, palm rest of laptop, chassis of mobile phone and liquid crystal touch panel.

**Table 1a. Amines formed from Azocolorants and Azodyes**

Specified Amines	CAS No.
biphenyl-4-ylamine	92-67-1
Benzidine	92-87-5
4-chloro-o-toluidine	95-69-2
2-naphthylamine	91-59-8
o-aminoazotoluene	97-56-3
5-nitro-o-toluidine	99-55-8
4-chloroaniline	106-47-8
4-methoxy-m-phenylenediamine	615-05-4
4,4'-methylenedianiline	101-77-9
3,3'-dichlorobenzidine	91-94-1
3,3'-dimethoxybenzidine	119-90-4
3,3'-dimethylbenzidine	119-93-7
4,4'-methylenedi-o-toluidine	838-88-0
6-methoxy-m-toluidine	120-71-8
4,4'-methylene-bis(2-chloroaniline)	101-14-4
4,4'-oxydianiline	101-80-4

Specified Amines	CAS No.
4,4'-thiodianiline	139-65-1
o-toluidine	95-53-4
4-methyl-m-phenylenediamine	95-80-7
2,4,5-trimethylaniline	137-17-7
o-anisidine	90-04-0
4-amino azobenzene	60-09-3

**Table 1b. Ozone depleting Substances**

Substance Name		CAS No.
CFCs (Chlorofluorocarbons)	CFC-11	75-69-4
	CFC-12	75-71-8
	CFC-13	75-72-9
	CFC-111	354-56-3
	CFC-112	76-12-0 76-11-9
	CFC-113	76-13-1 354-58-5 26523-64-8
	CFC-114	76-14-2 1320-37-2 374-07-2
	CFC-115	76-15-3
	CFC-211	422-78-6 422-81-1 135401-87-5
	CFC-212	3182-26-1 134452-44-1
	CFC-213	134237-31-3 2354-06-5
	CFC-214	29255-31-0 2268-46-4
	CFC-215	1599-41-3 76-17-5 4259-43-2 1652-81-9 812-30-6
	CFC-216	661-97-2
CFC-217	422-86-6	
Halons	Halon-1011 (Bromochloromethane)	74-97-5
	Halon-1202	75-61-6
	Halon-1211	353-59-3
	Halon-1301	75-63-8
	Halon-2402	124-73-2 25497-30-7 27336-23-8
Tetrachloromethane (Carbon tetrachloride)		56-23-5
1,1,1-Trichloroethane (Methylchloroform)		71-55-6
Bromomethane (Methyl bromide)		74-83-9
Bromoethane (Ethyl bromide)		74-96-4
1-Bromopropane (n-propyl bromide)		106-94-5
Trifluoroiodomethane (Trifluoromethyl iodide)		2314-97-8
Chloromethane (Methyl chloride)		74-87-3
HBFCs (Hydrobromofluorocarbons)	Dibromofluoromethane (HBFC-21 B2)	1868-53-7
	Bromodifluoromethane (HBFC-22 B1)	1511-62-2
	Bromofluoromethane (HBFC-31 B1)	373-52-4
	Tetrabromofluoroethane (HBFC-121 B4)	306-80-9 353-93-5

Tribromodifluoroethane (HBFC-122 B3)	353-97-9 677-34-9 7304-53-2
Dibromotrifluoroethane (HBFC-123 B2)	354-04-1
Bromotetrafluoroethane (HBFC-124 B1)	124-72-1
Tribromofluoroethane (HBFC-131 B3)	420-88-2 598-67-4
Dibromodifluoroethane (HBFC-132 B2)	75-82-1 359-19-3
Bromotrifluoroethane (HBFC-133 B1)	421-06-7
Dibromofluoroethane (HBFC-141 B2)	358-97-4
Bromodifluoroethane (HBFC-142 B1)	420-47-3 359-07-9
Bromofluoroethane (HBFC-151 B1)	762-49-2
Hexabromofluoropropane (HBFC-221 B6)	-
Pentabromodifluoropropane (HBFC-222 B5)	-
Tetrabromotrifluoropropane (HBFC-223 B4)	-
Tribromotetrafluoropropane (HBFC-224 B3)	666-48-8
Dibromopentafluoropropane (HBFC-225 B2)	431-78-7
Bromohexafluoropropane (HBFC-226 B1)	2252-78-0
Pentabromofluoropropane (HBFC-231 B5)	-
Tetrabromodifluoropropane (HBFC-232 B4)	148875-98-3
Tribromotrifluoropropane (HBFC-233 B3)	421-90-9
Dibromotetrafluoropropane (HBFC-234 B2)	460-86-6
Bromopentafluoropropane (HBFC-235 B1)	460-88-8 22692-16-6 26391-11-7 422-01-5 53692-43-6 53692-44-7 677-52-1 677-53-2 679-94-7
Tetrabromofluoropropane (HBFC-241 B4)	148875-95-0
Tribromodifluoropropane (HBFC-242 B3)	70192-80-2 666-25-1
Dibromotrifluoropropane (HBFC-243 B2)	431-21-0
Bromotetrafluoropropane (HBFC-244 B1)	679-84-5 19041-01-1 29151-25-5 460-67-3 70192-71-1 70192-84-6
Tribromofluoropropane (HBFC-251 B3)	75372-14-4
Dibromodifluoropropane (HBFC-252 B2)	460-25-3
Bromotrifluoropropane (HBFC-253 B1)	421-46-5 460-32-2
Dibromofluoropropane (HBFC-261 B2) Bromodifluoropropane (HBFC-262 B1)	51584-26-0 1786-38-5 453-00-9 62135-10-8 62135-11-9 111483-20-6 2195-05-3 420-89-3 420-98-4 430-87-5 461-49-4
Bromofluoropropane (HBFC-271 B1)	1871-72-3 352-91-0

HCFCs (Hydrochlorofluorocarbons)	HCFC-21	75-43-4
	HCFC-22	75-45-6
	HCFC-31	593-70-4
	HCFC-121	134237-32-4 354-11-0 354-14-3
	HCFC-122	41834-16-6 354-21-2 354-15-4 354-12-1
	HCFC-123	34077-87-7 90454-18-5 306-83-2 354-23-4 812-04-4
	HCFC-124	63938-10-3 2837-89-0 354-25-6
	HCFC-131	27154-33-2 134237-34-6 359-28-4 811-95-0 2366-36-1
	HCFC-132	25915-78-0 1649-08-7 1842-05-3 471-43-2 431-06-1
	HCFC-133	1330-45-6 431-07-2 75-88-7 421-04-5
	HCFC-141	1717-00-6 25167-88-8 430-57-9 430-53-5
	HCFC-142	25497-29-4 338-65-8 75-68-3 338-64-7 55949-44-5
	HCFC-151	110587-14-9 762-50-5 1615-75-4
	HCFC-221	134237-35-7 29470-94-8 422-26-4
	HCFC-222	134237-36-8 422-49-1 422-30-0 116867-32-4
	HCFC-223	134237-37-9 422-52-6 422-50-4
	HCFC-224	134237-38-0 422-54-8 422-53-7 422-51-5

	HCFC-225	127564-92-5 128903-21-9 422-48-0 422-44-6 422-56-0 507-55-1 13474-88-9 431-86-7 136013-79-1 111512-56-2 2713-09-9
	HCFC-226	134308-72-8 431-87-8 28987-04-4
	HCFC-231	134190-48-0 421-94-3
	HCFC-232	134237-39-1 460-89-9
	HCFC-233	134237-40-4 7125-83-9
	HCFC-234	127564-83-4 425-94-5
	HCFC-235	134237-41-5 460-92-4 108662-83-5
	HCFC-241	134190-49-1 666-27-3
	HCFC-242	134237-42-6 460-63-9
	HCFC-243	134237-43-7 7125-99-7 338-75-0 460-69-5 116890-51-8
	HCFC-244	134190-50-4 679-85-6 421-75-0
	HCFC-251	134190-51-5 818-99-5 421-41-0
	HCFC-252	134190-52-6 819-00-1
	HCFC-253	134237-44-8 460-35-5 26588-23-8
	HCFC-261	134237-45-9 7799-56-6 420-97-3 127404-11-9
	HCFC-262	134190-53-7 420-99-5 102738-79-4 421-02-3
	HCFC-271	134190-54-8 420-44-0 430-55-7

**Table 1c. Polychlorinated Biphenyls (PCBs) and specific substitutes**

Substance Name	CAS No.
Polychlorinated Biphenyls (all isomers and congeners)	1336-36-3
Monomethyl-tetrachloro-diphenyl methane (Ugilec 141)	76253-60-6
Monomethyl-dichloro-diphenyl methane (Ugilec 121, Ugilec 21)	81161-70-8
Monomethyl-dibromo-diphenyl methane (DBBT)	99688-47-8

**Table 1d. Fluorinated Greenhouse Gases (HFC, PFC and SF6)**

Substance Name	CAS No.	
PFCs (Perfluorocarbons)	Carbon tetrafluoride (Perfluoromethane)	75-73-0
	Perfluoroethane (Hexafluoroethane)	76-16-4
	Perfluoropropane (Octafluoropropane)	76-19-7
	Perfluorobutane (Decafluorobutane)	355-25-9
	Perfluoropentane (Dodecafluoropentane)	678-26-2
	Perfluorohexane (Tetradecafluorohexane)	355-42-0
	Perfluorocyclobutane	115-25-3
Sulfur Hexafluoride (SF6)	2551-62-4	
HFCs (Hydrofluorocarbons)	Trifluoromethane (HFC-23)	75-46-7
	Difluoromethane (HFC-32)	75-10-5
	Methyl fluoride (HFC-41)	593-53-3
	2H,3H-Decafluoropentane (HFC-43-10mee)	138495-42-8
	Pentafluoroethane (HFC-125)	354-33-6
	1,1,2,2-Tetrafluoroethane (HFC-134)	359-35-3
	1,1,1,2-Tetrafluoroethane (HFC-134a)	811-97-2
	Difluoroethane	25497-28-3
	1,1-Difluoroethane (HFC-152a)	75-37-6
	1,2- Difluoroethane	624-72-6
	Trifluoroethane	27987-06-0
	1,1,2-Trifluoroethane (HFC-143)	430-66-0
	1,1,1-Trifluoroethane (HFC-143a)	420-46-2
	2H-Heptafluoropropane (HFC-227ea)	431-89-0
	1,1,1,2,2,3,3- Heptafluoropropane	2252-84-8
	1,1,1,2,2,3-Hexafluoro-propane (HFC-236cb)	677-56-5
	1,1,1,2,3,3-Hexafluoropropane (HFC-236ea)	431-63-0
	Hexafluoropropane	27070-61-7
	1,1,1,3,3,3-Hexafluoropropane (HFC-236fa)	690-39-1
	1,1,2,2,3-Pentafluoropropane (HFC-245ca)	679-86-7
1,1,1,3,3-Pentafluoropropane (HFC-245fa)	460-73-1	
1,1,1,2,2- Pentafluoropropane	1814-88-6	
1,1,1,3,3-Pentafluorobutane (HFC-365mfc)	406-58-6	

**Table 1e.. Polycyclic aromatic hydrocarbons (PAH)**

Substance Name	CAS No.
Benzo[a]pyrene (BaP)	50-32-8
Benzo[e]pyrene (BeP)	192-97-2
Benzo[a]anthracene (BaA)	56-55-3
Chrysen (CHR)	218-01-9
Benzo[b]fluoranthene (BbFA)	205-99-2
Benzo[j]fluoranthene (BjFA)	205-82-3
Benzo[k]fluoranthene (BkFA)	207-08-9
Dibenzo[a,h]anthracene(DBAhA)	53-70-3



**Table 1f. Hexabromocyclododecane (HBCDD)**

Substance Name	CAS No.
Hexabromocyclododecane	25637-99-4
	4736-49-6
	65701-47-5
	138257-17-7
	138257-18-8
	138257-19-9
	169102-57-2
	678970-15-5
	678970-16-6
678970-17-7	
1,2,5,6,9,10-hexabromocyclododecane	3194-55-6
$\alpha$ -hexabromocyclododecane	134237-50-6
$\beta$ -hexabromocyclododecane	134237-51-7
$\gamma$ -hexabromocyclododecane	134237-52-8

**Table 1g. Exempted Applications (Exemption from the Banned Standards shown in Table 1)**

No	Substance Name	Exempted Application (The number in this column is the exemption number described in RoHS directive.)
A003	Cadmium / Cadmium Compounds	<del>8(a). Cadmium and its compounds in one shot pellet type thermal cut-offs (Expires on 1 January 2012)</del>
		8(b). Cadmium and its compounds in electrical contacts
		13(b). Cadmium in filter glasses and glasses used for reflectance standards
A005	Lead/Lead Compounds	5(a). Lead in the glass of cathode ray tubes
		5(b). Lead in glass of fluorescent tubes not exceeding 0.2% by weight
		6(a). Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35% lead by weight
		6(b). Lead as an alloying element in aluminium containing up to 0,4% lead by weight
		6(c). Copper alloy containing up to 4% lead by weight
		7(a). Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).
		7(b). Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.
		7(c)-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
		7(c)-II. Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
		<del>7(c)-III. Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC (Expires on 1 January 2013)</del>
		9(b). Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications
<del>11(b). Lead used in other than C-press compliant pin connector systems (Expires on 1 January 2013)</del>		

No	Substance Name	Exempted Application (The number in this column is the exemption number described in RoHS directive.)
		<del>14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight. (Expires on 4 June 2014)</del> 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages. 13(a). Lead in white glasses used for optical applications 13(b). Lead in filter glasses and glasses used for reflectance standards
A006	Mercury/Mercury Compounds	Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp) 3(a). Short length ( ≤ 500 mm ) : 3.5mg may be used per lamp 3(b). Medium length ( > 500mm and ≤ 1500 mm ) : 5mg may be used per lamp 3(c). Long length (> 1500 mm) : 13mg may be used per lamp
A008	PFOS / PFOS-related substances	<ul style="list-style-type: none"> <li>- PFOS in photoresists or anti reflective coatings for photolithography processes</li> <li>- PFOS in photographic coatings applied to films, papers, or printing plates</li> </ul>
A017	Dibutyltin compounds (DBT)	<ul style="list-style-type: none"> <li>- One-component and two-component room temperature vulcanisation sealants (RTV-1 and RTV-2 sealants) and adhesives(Expires on 2 January 2015)</li> <li>- Paints and coatings containing DBT compounds as catalysts when applied on articles(Expires on 2 January 2015)</li> </ul>

**“Table 2: C. Specific Banned Substances in Japan”**

No	Substance Name	Banned Standards	Remarks
C001	Polychlorinated Naphthalenes (more than 3 chlorine atoms)	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C002	Hexachlorobenzene	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C003	Aldrin	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C004	Dieldrin	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C005	Endrin	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C006	DDT (Chlorophenothane)	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C007	Chlordanes	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C008	N,N'-ditolyl-p-phenylenediamine, N-tolyl-N'-xylyl-p-phenylenediamine and N,N'-dixylyl-p-phenylenediamine	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C009	2,4,6-tri-tert-butylphenol	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	
C010	Toxaphene	<ol style="list-style-type: none"> <li>1. Ban of Intentional Addition</li> <li>2. Ban of attachment, mix, or production of the substances in the manufacturing process.</li> </ol>	

No	Substance Name	Banned Standards	Remarks
C011	Mirex	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C012	Kelthane	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C013	Hexachloro-1,3-butadiene	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C014	2-(2H-benzotriazol-2-yl)-4,6-di-tert-butylphenol	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C015	Pentachlorobenzene	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C016	$\alpha$ -Hexachlorocyclohexane	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C017	$\beta$ -Hexachlorocyclohexane	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C018	$\gamma$ -Hexachlorocyclohexane	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C019	Chlordecone	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	
C020	PFOA, PFOA-salts, PFOA-esters Details: Table 2a.	<p>&lt;Chemical products and specific cases&gt;</p> <ol style="list-style-type: none"> <li>Ban of Intentional Addition</li> <li>Ban of attachment, mix, or production of the substances in the manufacturing process.</li> <li>Concentration or content must not exceed the following levels as impurities. <ul style="list-style-type: none"> <li>-Chemical products:0.001% by weight</li> <li>-fiber, carpet, or other coated articles:1<math>\mu</math>g/ m<sup>2</sup></li> </ul> </li> </ol> <p>&lt;Article&gt; Concentration in product must not exceed 0.1% by weight.</p>	In force from 1st June 2014 Exempted Application: Table 2b.
C021	Endosulfan	1. Ban of Intentional Addition 2. Ban of attachment, mix, or production of the substances in the manufacturing process.	

**Table.2a. PFOA, PFOA-salts, PFOA-esters**

Substance Name	CAS No.
PFOA - perfluorooctanoic acid	335-67-1
Ammonium salt of PFOA	3825-26-1
Perfluorooctanoic acid sodium salt; Sodium salt of PFOA	335-95-5
Potassium salt of PFOA	2395-00-8
Silver salt of PFOA	335-93-3
Pentadecafluorooctyl fluoride	335-66-0
Pentadecafluoro-octanoicacimethylester	376-27-2
Pentadecafluoro-octanoicaciethylester	3108-24-5

**Table.2b. Exempted Applications (Exemption from the Banned Standards shown in Table 2)**

No	Substance Name	Exempted Application
C020	PFOA, PFOA-salts, PFOA-esters	<ul style="list-style-type: none"><li>• Photographic coatings for film, paper or screen (Expires on 31 December 2015)</li><li>• Adhesive, foil, or tape in semiconductors (Expires on 31December 2015)</li></ul>